SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

SDLS003 D2632. JANUARY 1981 - REVISED MARCH 1988 SN54LS590, SN54LS591...J OR W PACKAGE

- 8-Bit Counter with Register
- Parallel Register Outputs

schematics of inputs and outputs

- Choice of 3-State ('LS590) or Open-Collector ('LS591) Register Outputs
- Guaranteed Counter Frequency: DC to 20 MHz

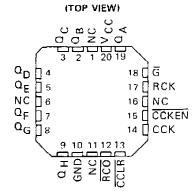
description

These devices each contain an 8-bit binary counter that feeds an 8 bit storage register. The storage register has parallel outputs. Separate clocks are provided for both the binary counter and storage register. The binary counter features a direct clear input CCLR and a count enable input CCKEN. For cascading, a ripple carry output RCO is provided. Expansion is easily accomplished for two stages by connecting RCO of the first stage to CCKEN of the second stage. Cascading for larger count chains can be accomplished by connecting RCO of each stage to CCK of the following stage.

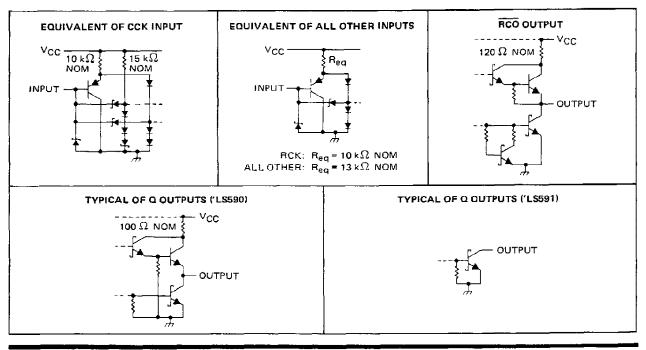
Both the counter and register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the counter state will always be one count ahead of the register. Internal circuitry prevents clocking from the clock enable.

SN74LS590, SN74L	N PACKAGE	
(TOP	VIEW)	
ов []		Vcc
QC []2	15	0 _A
Q _D []₃	14 🗍	G
QE ∐4	13	RCK
QF [5	12	CCKEN
Q G 🗍 6	11	сск
₽н[]7	10	CCLR
GND 🛛	9	RCO

SN54LS590, SN54LS591 . . . FK PACKAGE



NC - No internal connection

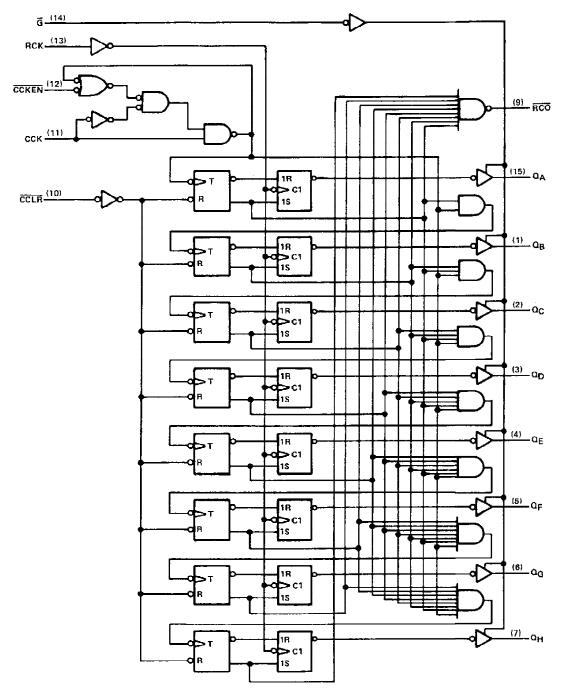


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SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

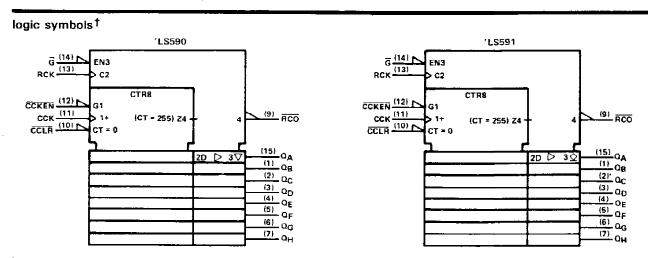
logic diagram (positive logic)



Pin numbers shown are for J, N and W packages.



SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS



 $^\dagger These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for J, N, and W packages.$

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7V
Input voltage	
Off-state output voltage	
Operating free-air temperature range: SN54LS590, SN54LS591	
SN74LS590, SN74LS591	\dots 0°C to 70°C
Storage temperature range	–65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

			:	SN54LS			SN74LS	•		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage		2			2			V	
VIL	Low-level input voltage				0.7			0.8	V	
Voн	High-level output voltage	Q, 'LS591 only	1		5.5	1		5.5	V	
Inu	High-level output current	RCO	1		1			- 1		
юн	ingi icizi sarpat carrent	Q, (L\$590 only	1		- 1			- 2.6	mΑ	
10L	Low-level output current	RCO			8			16		
		Q			12			24	mA	
fock	Counter clock frequency		0	-	20	0		20	MHz	
frck	Register clock frequency		0		25	0		25	MHz	
^t w(CCK)	Duration of counter clock pu	lse	25			25			пѕ	
tw(CCLR)	Duration of counter clear puls	se	20			20			ns	
^t w(RCK)	Duration of register clock pul	se	20			20			<u>пs</u>	
		CCKEN low before CCK1	20			20				
t _{su}	Setup time	CCLR inactive before CCK1	20			20		<u> </u>	ns	
		CCK before RCK f (see Note 2)	40	*		40			1	
th	Hold time	CCKEN low after CCK1	0			0			ns	
TA	Operating free-air temperature	e	- 55		125	0		70	°C	

NOTE 2: This setup time ensures the register will see stable data from the counter outputs. The clocks may be tied together in which case the register state will be one clock pulse behind the counter.



SN54LS590, SN54LS591, SN74LS590, SN74LS591 8 BIT BINARY COUNTERS WITH OUTPUT REGISTERS

			I				SN54LS	,	SN74LS'				
F	PARAMETER			TEST CONDITIONS					MIN	TYP‡	MAX	UNIT	
Vik			Vcc = MIN,	1 ₁ = - 18 mA				- 1.5			- 1.5	v	
	11.55.00.0)/ - MIN		¹ OH = - 1 mA	2.4	3.2						
∨он	1LS590 C	!	V _{CC} = MIN,	v H - zv,	¹ OH = - 2.6 mA	1			2,4	3.1		V	
	RCO		VIL = MAX		^I OH = - 1 mA	2.4	3.2		2.4	3.2		_	
юн	'L\$591 C)	V _{CC} = MIN, V _{IL} - MAX	V _{IH} = 2 V,	V _{OH} = 5.5 V,			Q.1			0.1	mA	
					1 _{0L} = 12 mA	•	0.25	0.4		0.25	0.4		
	a		V _{CC} = MIN,	V _{IH} = 2 V,	1 _{0L} = 24 mA	+				0.35	0.5	v	
VOL						IOL = 8 mA	1	0,25	0.4		0.25	0.4	0.4
				I _{OL} = 16 mA					0.35	0.5			
Iоzн	'LS590 C	1	V _{CC} = MAX, V _O = 2.7 V	V _{IH} = 2 V,	V _{IL} = MAX,			20			20	μA	
I _{OZL}	′L\$590 C	1		V _{1H} = 2 V.	VIL = MAX,		·	- 20			- 20	μA	
	i		V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mΑ	
і. Пн			V _{CC} = MAX,					20	T		20	μA	
	сск							- 0,8	1		- 0.8	mA	
ΊL	All other	5	V _{CC} = MAX,	V ₁ = 0.4 V	V ₁ = 0.4 V			- 0.2		•	- 0.2		
	1L\$590 C	1	11 . KGA V	<u> </u>		- 30		- 130	- 30		- 130	mA	
los§	RCO		Vcc÷MAX,	v0-0 v		- 20		- 100	- 20		- 100	ША	
		1ссн					33	55		33	55		
	'LS590	ICCL	V _{CC} = MAX,				44	65		44			
lcc		lccz] All possible inp	All possible inputs grounded,			46	65		46	65	mΑ	
	'L\$591	1ссн	All outputs ope	en .		L	35	55		35			
	20001	ICCL]				42	65		42	65		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions, ‡ All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ § Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second,

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

	FROM	то		TEST CONDITIONS)	'LS591			UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST COND	DITIONS	MIN	TYP	MAX	MIN	түр	MAX	UNIT
fmax	RCK	a	R _L = 667 Ω,	C _L = 45 pF	20	35		20	35		MHz
^t PLH	CCKT	RCO	D (1) D	C _L = 30 pF	Ī	14	22		16	24	ns
^t PHL	CCKt	RCO	R _L = 1 kΩ,			20	30		25	38	ns
tPLH	CCLR	RCO				30	45		32	48	ns
^t PLH	RCK1	Q	D (107) (1	0 - 15 - 5	İ	12	18		25	38	ns
tPHL	RCKt					22	33		28	42	ns
tpzh	Ğı	<u>a</u>	$R_L = 667 \Omega$,	CL = 45 pF	-	25	38				ns
tpzl	Ğ∔	<u>a</u>				30	45				ns
t _{PHZ}	<u>G</u> t	Q		2 5 5		20	30				ns
^t PLZ	Gt	<u>a</u>	RL=667Ω.	CL = 5 pF		25	38				ns
tpLH	Gt	<u> </u>			1				34	50	ns
tPHL I	Ğ↓		R _L = 667 Ω,	C _L = 45 pF			-		32	48	ាទ

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	(3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-87517012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87517012A SNJ54LS 590FK
5962-8751701EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8751701EA SNJ54LS590J
5962-8751701EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8751701EA SNJ54LS590J
SN54LS590J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS590J
SN54LS590J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS590J
SN74LS590D	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS590
SN74LS590D	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS590
SN74LS590N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS590N
SN74LS590N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS590N
SN74LS590NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS590
SN74LS590NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS590
SNJ54LS590FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87517012A SNJ54LS 590FK
SNJ54LS590FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87517012A SNJ54LS 590FK
SNJ54LS590J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8751701EA SNJ54LS590J
SNJ54LS590J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8751701EA SNJ54LS590J

⁽¹⁾ **Status:** For more details on status, see our product life cycle.



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PACKAGE OPTION ADDENDUM

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54LS590, SN74LS590 :

Catalog : SN74LS590

Military : SN54LS590

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



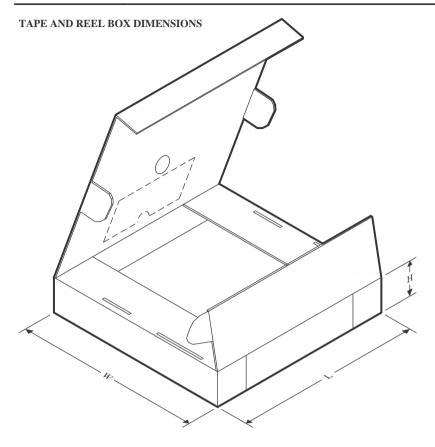
*All dimensions are nominal												
Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS590NSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

7-Dec-2024



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS590NSR	SOP	NS	16	2000	356.0	356.0	35.0

TEXAS INSTRUMENTS

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7-Dec-2024

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-87517012A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74LS590D	D	SOIC	16	40	507	8	3940	4.32
SN74LS590N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS590N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS590FK	FK	LCCC	20	55	506.98	12.06	2030	NA

NS0016A



PACKAGE OUTLINE

SOP - 2.00 mm max height

SOP



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- Per ASME Y14.5M.
 This drawing is subject to change without notice.
 This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



NS0016A

EXAMPLE BOARD LAYOUT

SOP - 2.00 mm max height

SOP



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



NS0016A

EXAMPLE STENCIL DESIGN

SOP - 2.00 mm max height

SOP



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



FK 20

8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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